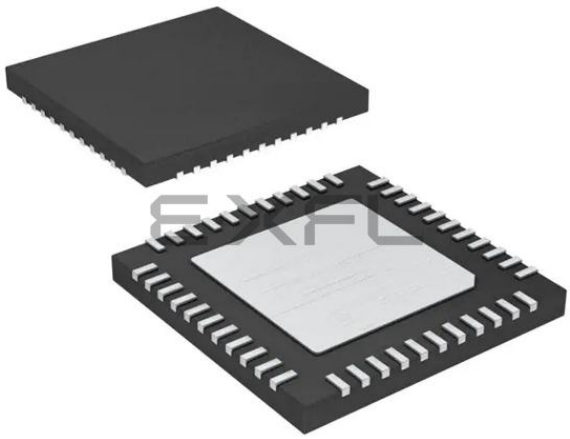

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	40MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, HLVD, POR, PWM, WDT
Number of I/O	36
Program Memory Size	64KB (32K x 16)
Program Memory Type	FLASH
EEPROM Size	1K x 8
RAM Size	3.8K x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	A/D 13x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VQFN Exposed Pad
Supplier Device Package	44-QFN (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18lf4620t-i-ml

3.0 POWER-MANAGED MODES

PIC18F2525/2620/4525/4620 devices offer a total of seven operating modes for more efficient power management. These modes provide a variety of options for selective power conservation in applications where resources may be limited (i.e., battery-powered devices).

There are three categories of power-managed modes:

- Run modes
- Idle modes
- Sleep mode

These categories define which portions of the device are clocked and sometimes, what speed. The Run and Idle modes may use any of the three available clock sources (primary, secondary or internal oscillator block); the Sleep mode does not use a clock source.

The power-managed modes include several power-saving features offered on previous PIC® devices. One is the clock switching feature, offered in other PIC18 devices, allowing the controller to use the Timer1 oscillator in place of the primary oscillator. Also included is the Sleep mode, offered by all PIC devices, where all device clocks are stopped.

3.1 Selecting Power-Managed Modes

Selecting a power-managed mode requires two decisions: if the CPU is to be clocked or not and the selection of a clock source. The IDLEN bit (OSCCON<7>) controls CPU clocking, while the SCS1:SCS0 bits (OSCCON<1:0>) select the clock source. The individual modes, bit settings, clock sources and affected modules are summarized in Table 3-1.

3.1.1 CLOCK SOURCES

The SCS1:SCS0 bits allow the selection of one of three clock sources for power-managed modes. They are:

- the primary clock, as defined by the FOSC3:FOSC0 Configuration bits
- the secondary clock (the Timer1 oscillator)
- the internal oscillator block (for RC modes)

3.1.2 ENTERING POWER-MANAGED MODES

Switching from one power-managed mode to another begins by loading the OSCCON register. The SCS1:SCS0 bits select the clock source and determine which Run or Idle mode is to be used. Changing these bits causes an immediate switch to the new clock source, assuming that it is running. The switch may also be subject to clock transition delays. These are discussed in **Section 3.1.3 "Clock Transitions and Status Indicators"** and subsequent sections.

Entry to the power-managed Idle or Sleep modes is triggered by the execution of a SLEEP instruction. The actual mode that results depends on the status of the IDLEN bit.

Depending on the current mode and the mode being switched to, a change to a power-managed mode does not always require setting all of these bits. Many transitions may be done by changing the oscillator select bits, or changing the IDLEN bit, prior to issuing a SLEEP instruction. If the IDLEN bit is already configured correctly, it may only be necessary to perform a SLEEP instruction to switch to the desired mode.

TABLE 3-1: POWER-MANAGED MODES

Mode	OSCCON Bits<7,1:0>		Module Clocking		Available Clock and Oscillator Source
	IDLEN(1)	SCS1:SCS0	CPU	Peripherals	
Sleep	0	N/A	Off	Off	None – All clocks are disabled
PRI_RUN	N/A	00	Clocked	Clocked	Primary – LP, XT, HS, HSPLL, RC, EC and Internal Oscillator Block(2). This is the normal full-power execution mode.
SEC_RUN	N/A	01	Clocked	Clocked	Secondary – Timer1 Oscillator
RC_RUN	N/A	1x	Clocked	Clocked	Internal Oscillator Block(2)
PRI_IDLE	1	00	Off	Clocked	Primary – LP, XT, HS, HSPLL, RC, EC
SEC_IDLE	1	01	Off	Clocked	Secondary – Timer1 Oscillator
RC_IDLE	1	1x	Off	Clocked	Internal Oscillator Block(2)

Note 1: IDLEN reflects its value when the SLEEP instruction is executed.

2: Includes INTOSC and INTOSC postscaler, as well as the INTRC source.

6.3 Reading the Data EEPROM Memory

To read a data memory location, the user must write the address to the EEADRH:EEADR register pair, clear the EEPGD control bit (EECON1<7>) and then set control bit, RD (EECON1<0>). The data is available on the very next instruction cycle; therefore, the EEDATA register can be read by the next instruction. EEDATA will hold this value until another read operation, or until it is written to by the user (during a write operation).

The basic process is shown in Example 6-1.

6.4 Writing to the Data EEPROM Memory

To write an EEPROM data location, the address must first be written to the EEADRH:EEADR register pair and the data written to the EEDATA register. The sequence in Example 6-2 must be followed to initiate the write cycle.

The write will not begin if this sequence is not exactly followed (write 55h to EECON2, write 0AAh to EECON2, then set WR bit) for each byte. It is strongly recommended that interrupts be disabled during this code segment.

Additionally, the WREN bit in EECON1 must be set to enable writes. This mechanism prevents accidental writes to data EEPROM due to unexpected code execution (i.e., runaway programs). The WREN bit should be kept clear at all times, except when updating the EEPROM. The WREN bit is not cleared by hardware.

After a write sequence has been initiated, EECON1, EEADRH:EEADR and EEDATA cannot be modified. The WR bit will be inhibited from being set unless the WREN bit is set. The WREN bit must be set on a previous instruction. Both WR and WREN cannot be set with the same instruction.

At the completion of the write cycle, the WR bit is cleared in hardware and the EEPROM Interrupt Flag bit, EEIF, is set. The user may either enable this interrupt, or poll this bit. EEIF must be cleared by software.

6.5 Write Verify

Depending on the application, good programming practice may dictate that the value written to the memory should be verified against the original value. This should be used in applications where excessive writes can stress bits near the specification limit.

EXAMPLE 6-1: DATA EEPROM READ

```
        MOVLW    DATA_EE_ADDRH     ;
        MOVWF    EEADRH            ; Upper bits of Data Memory Address to read
        MOVLW    DATA_EE_ADDR      ;
        MOVWF    EEADR             ; Lower bits of Data Memory Address to read
        BCF      EECON1, EEPGD     ; Point to DATA memory
        BCF      EECON1, CFGS      ; Access EEPROM
        BSF      EECON1, RD        ; EEPROM Read
        MOVF     EEDATA, W         ; W = EEDATA
```

EXAMPLE 6-2: DATA EEPROM WRITE

```
                 MOVLW   DATA_EE_ADDRH     ;
                 MOVWF   EEADRH            ; Upper bits of Data Memory Address to write
                 MOVLW   DATA_EE_ADDR      ;
                 MOVWF   EEADR             ; Lower bits of Data Memory Address to write
                 MOVLW   DATA_EE_DATA      ;
                 MOVWF   EEDATA            ; Data Memory Value to write
                 BCF     EECON1, EPGD      ; Point to DATA memory
                 BCF     EECON1, CFGS      ; Access EEPROM
                 BSF     EECON1, WREN      ; Enable writes

                 BCF     INTCON, GIE       ; Disable Interrupts
                 MOVLW   55h               ;
Required         MOVWF   EECON2            ; Write 55h
Sequence         MOVLW   0AAh              ;
                 MOVWF   EECON2            ; Write 0AAh
                 BSF     EECON1, WR        ; Set WR bit to begin write
                 BSF     INTCON, GIE       ; Enable Interrupts

                                           ; User code execution
                 BCF     EECON1, WREN      ; Disable writes on write complete (EEIF set)
```

7.0 FLASH PROGRAM MEMORY

The Flash program memory is readable, writable and erasable during normal operation over the entire VDD range.

A read from program memory is executed on one byte at a time. A write to program memory is executed on blocks of 64 bytes at a time. Program memory is erased in blocks of 64 bytes at a time. A bulk erase operation may not be issued from user code.

Writing or erasing program memory will cease instruction fetches until the operation is complete. The program memory cannot be accessed during the write or erase, therefore, code cannot execute. An internal programming timer terminates program memory writes and erases.

A value written to program memory does not need to be a valid instruction. Executing a program memory location that forms an invalid instruction results in a NOP.

7.1 Table Reads and Table Writes

In order to read and write program memory, there are two operations that allow the processor to move bytes between the program memory space and the data RAM:

- Table Read (TBLRD)
- Table Write (TBLWT)

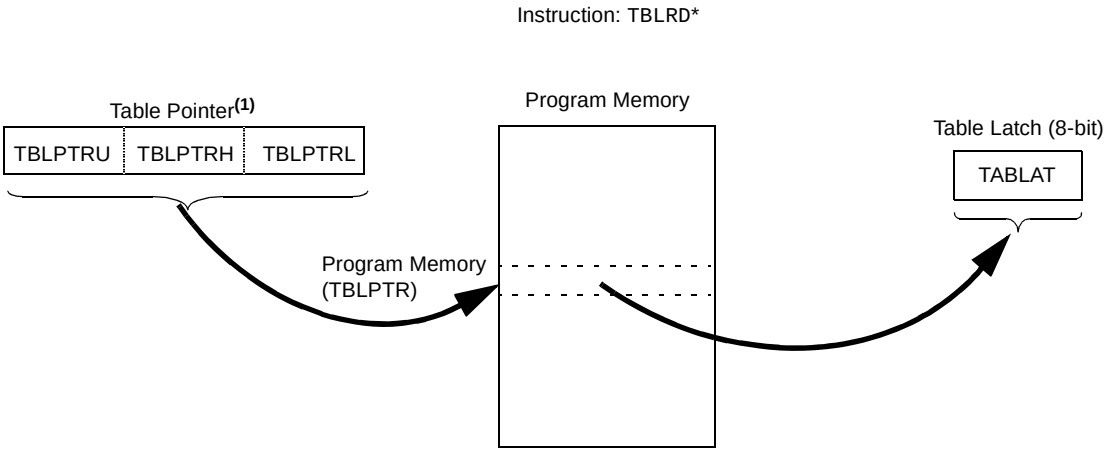
The program memory space is 16 bits wide, while the data RAM space is 8 bits wide. Table reads and table writes move data between these two memory spaces through an 8-bit register (TABLAT).

Table read operations retrieve data from program memory and place it into the data RAM space. Figure 7-1 shows the operation of a table read with program memory and data RAM.

Table write operations store data from the data memory space into holding registers in program memory. The procedure to write the contents of the holding registers into program memory is detailed in **Section 7.5 “Writing to Flash Program Memory”**. Figure 7-2 shows the operation of a table write with program memory and data RAM.

Table operations work with byte entities. A table block containing data, rather than program instructions, is not required to be word aligned. Therefore, a table block can start and end at any byte address. If a table write is being used to write executable code into program memory, program instructions will need to be word-aligned.

FIGURE 7-1: TABLE READ OPERATION



Note 1: Table Pointer register points to a byte in program memory.

7.4 Erasing Flash Program Memory

The minimum erase block is 32 words or 64 bytes. Only through the use of an external programmer, or through ICSP control, can larger blocks of program memory be bulk erased. Word erase in the Flash array is not supported.

When initiating an erase sequence from the micro-controller itself, a block of 64 bytes of program memory is erased. The Most Significant 16 bits of the TBLPTR<21:6> point to the block being erased. TBLPTR<5:0> are ignored.

The EECON1 register commands the erase operation. The EEPGD bit must be set to point to the Flash program memory. The WREN bit must be set to enable write operations. The FREE bit is set to select an erase operation.

For protection, the write initiate sequence for EECON2 must be used.

A long write is necessary for erasing the internal Flash. Instruction execution is halted while in a long write cycle. The long write will be terminated by the internal programming timer.

7.4.1 FLASH PROGRAM MEMORY ERASE SEQUENCE

The sequence of events for erasing a block of internal program memory location is:

1. Load Table Pointer register with address of row being erased.
2. Set the EECON1 register for the erase operation:
   - set EEPGD bit to point to program memory;
   - clear the CFGS bit to access program memory;
   - set WREN bit to enable writes;
   - set FREE bit to enable the erase.
3. Disable interrupts.
4. Write 55h to EECON2.
5. Write 0AAh to EECON2.
6. Set the WR bit. This will begin the row erase cycle.
7. The CPU will stall for duration of the erase (about 2 ms using internal timer).
8. Re-enable interrupts.

EXAMPLE 7-2: ERASING A FLASH PROGRAM MEMORY ROW

```
                MOVLW   CODE_ADDR_UPPER         ; load TBLPTR with the base
                MOVWF   TBLPTRU                 ; address of the memory block
                MOVLW   CODE_ADDR_HIGH
                MOVWF   TBLPTRH
                MOVLW   CODE_ADDR_LOW
                MOVWF   TBLPTRL
    ERASE_ROW
                BSF     EECON1, EEPGD           ; point to Flash program memory
                BCF     EECON1, CFGS            ; access Flash program memory
                BSF     EECON1, WREN            ; enable write to memory
                BSF     EECON1, FREE            ; enable Row Erase operation
                BCF     INTCON, GIE             ; disable interrupts
Required        MOVLW   55h
Sequence        MOVWF   EECON2                  ; write 55h
                MOVLW   0AAh
                MOVWF   EECON2                  ; write 0AAh
                BSF     EECON1, WR              ; start erase (CPU stall)
                BSF     INTCON, GIE             ; re-enable interrupts
```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NOTES:

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FIGURE 17-5: SPI MODE WAVEFORM (SLAVE MODE WITH CKE = 0)

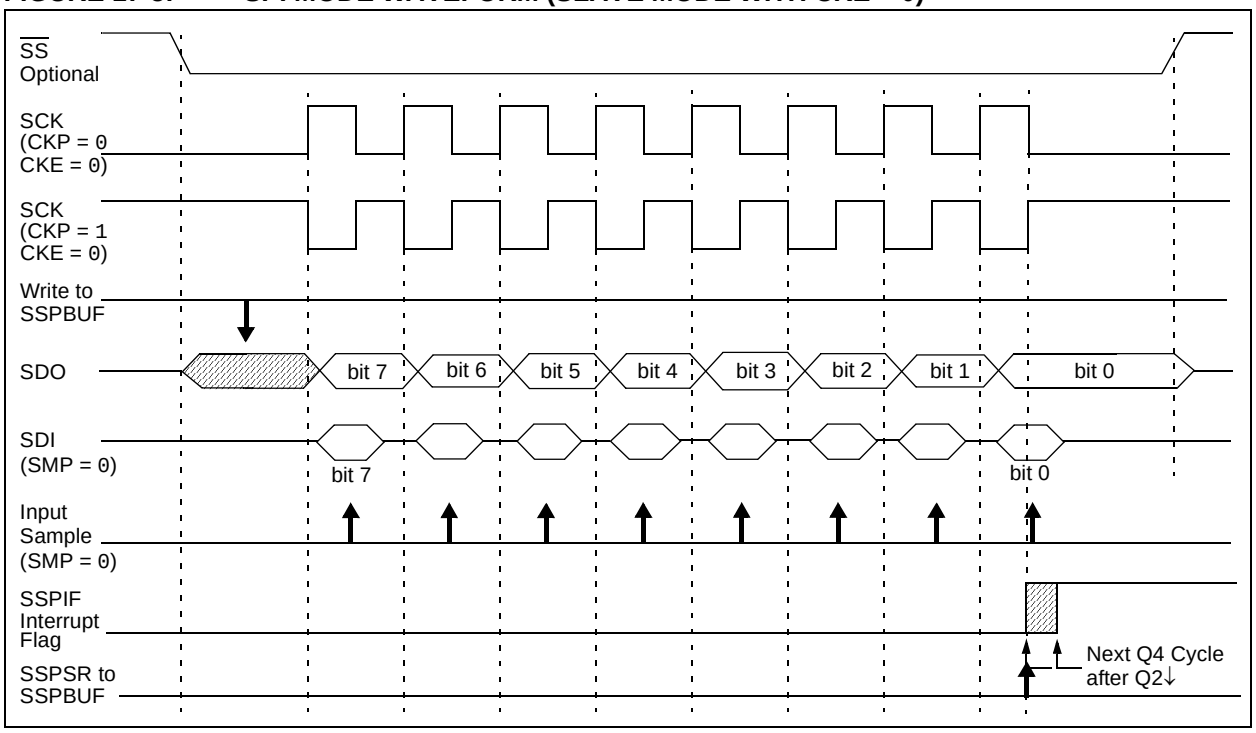
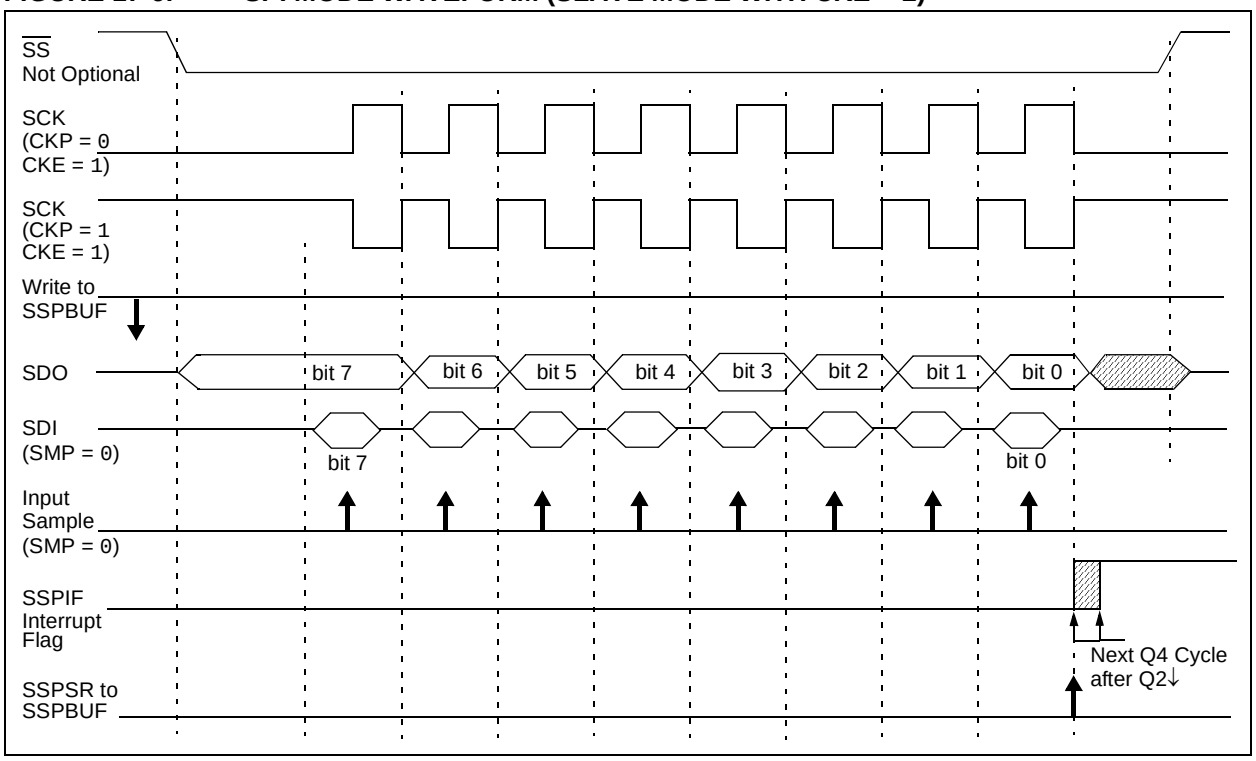


FIGURE 17-6: SPI MODE WAVEFORM (SLAVE MODE WITH CKE = 1)



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17.4.3.2 Reception

When the R/$\overline{W}$ bit of the address byte is clear and an address match occurs, the R/$\overline{W}$ bit of the SSPSTAT register is cleared. The received address is loaded into the SSPBUF register and the SDA line is held low ($\overline{ACK}$).

When the address byte overflow condition exists, then the no Acknowledge ($\overline{ACK}$) pulse is given. An overflow condition is defined as either bit, BF (SSPSTAT<0>), is set, or bit, SSPOV (SSPCON1<6>), is set.

An MSSP interrupt is generated for each data transfer byte. Flag bit, SSPIF (PIR1<3>), must be cleared in software. The SSPSTAT register is used to determine the status of the byte.

If SEN is enabled (SSPCON2<0> = 1), RC3/SCK/SCL will be held low (clock stretch) following each data transfer. The clock must be released by setting bit, CKP (SSPCON<4>). See **Section 17.4.4 "Clock Stretching"** for more detail.

17.4.3.3 Transmission

When the R/$\overline{W}$ bit of the incoming address byte is set and an address match occurs, the R/$\overline{W}$ bit of the SSPSTAT register is set. The received address is loaded into the SSPBUF register. The $\overline{ACK}$ pulse will be sent on the ninth bit and the RC3/SCK/SCL pin is held low regardless of SEN (see **Section 17.4.4 "Clock Stretching"** for more detail). By stretching the clock, the master will be unable to assert another clock pulse until the slave is done preparing the transmit data. The transmit data must be loaded into the SSPBUF register which also loads the SSPSR register. Then the RC3/SCK/SCL pin should be enabled by setting bit, CKP (SSPCON1<4>). The eight data bits are shifted out on the falling edge of the SCL input. This ensures that the SDA signal is valid during the SCL high time (Figure 17-9).

The $\overline{ACK}$ pulse from the master-receiver is latched on the rising edge of the ninth SCL input pulse. If the SDA line is high (not $\overline{ACK}$), then the data transfer is complete. In this case, when the $\overline{ACK}$ is latched by the slave, the slave logic is reset and the slave monitors for another occurrence of the Start bit. If the SDA line was low ($\overline{ACK}$), the next transmit data must be loaded into the SSPBUF register. Again, the RC3/SCK/SCL pin must be enabled by setting bit CKP.

An MSSP interrupt is generated for each data transfer byte. The SSPIF bit must be cleared in software and the SSPSTAT register is used to determine the status of the byte. The SSPIF bit is set on the falling edge of the ninth clock pulse.

17.4.17.1 Bus Collision During a Start Condition

During a Start condition, a bus collision occurs if:

a) SDA or SCL are sampled low at the beginning of the Start condition (Figure 17-26).

b) SCL is sampled low before SDA is asserted low (Figure 17-27).

During a Start condition, both the SDA and the SCL pins are monitored.

If the SDA pin is already low, or the SCL pin is already low, then all of the following occur:

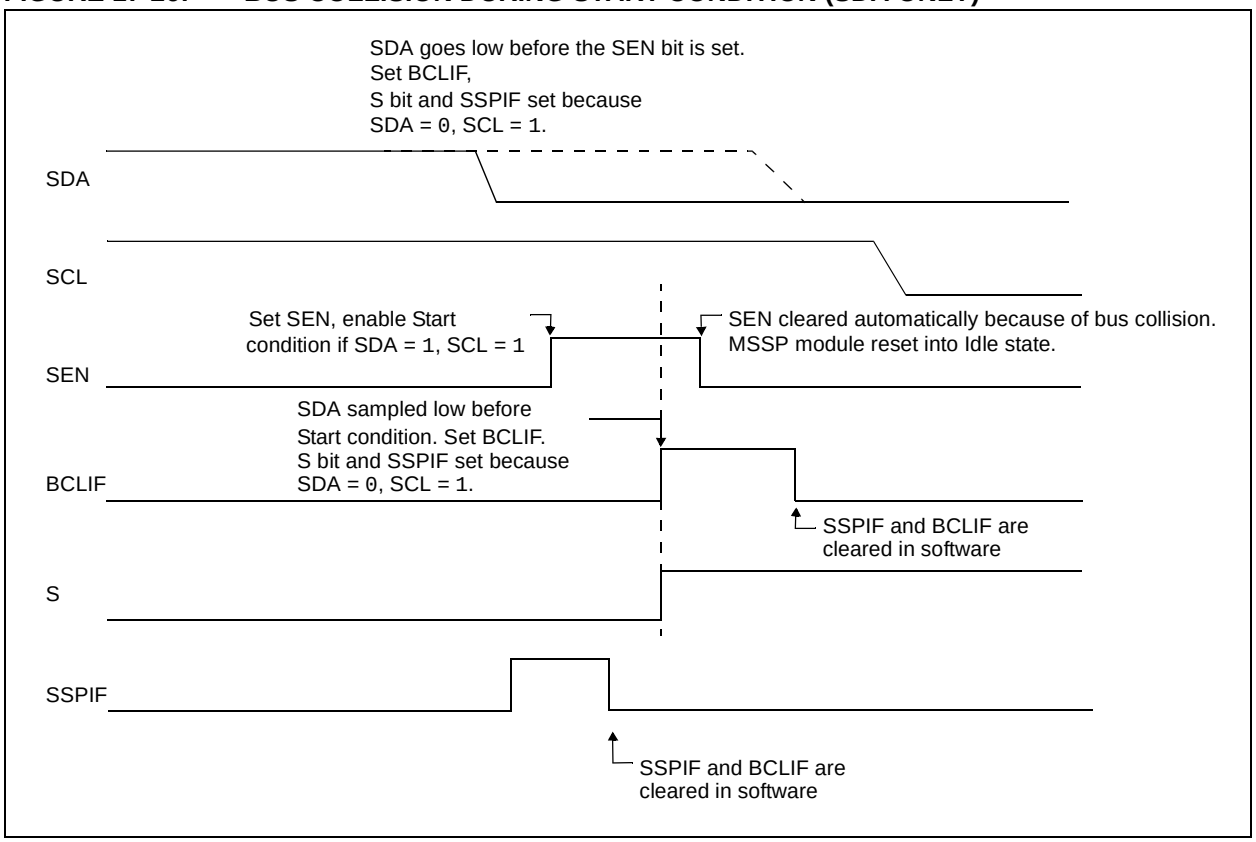
- the Start condition is aborted,
- the BCLIF flag is set and
- the MSSP module is reset to its Idle state (Figure 17-26).

The Start condition begins with the SDA and SCL pins deasserted. When the SDA pin is sampled high, the Baud Rate Generator is loaded from SSPADD<6:0> and counts down to 0. If the SCL pin is sampled low while SDA is high, a bus collision occurs because it is assumed that another master is attempting to drive a data '1' during the Start condition.

If the SDA pin is sampled low during this count, the BRG is reset and the SDA line is asserted early (Figure 17-28). If, however, a '1' is sampled on the SDA pin, the SDA pin is asserted low at the end of the BRG count. The Baud Rate Generator is then reloaded and counts down to 0; if the SCL pin is sampled as '0' during this time, a bus collision does not occur. At the end of the BRG count, the SCL pin is asserted low.

Note:	The reason that bus collision is not a factor during a Start condition is that no two bus masters can assert a Start condition at the exact same time. Therefore, one master will always assert SDA before the other. This condition does not cause a bus collision because the two masters must be allowed to arbitrate the first address following the Start condition. If the address is the same, arbitration must be allowed to continue into the data portion, Repeated Start or Stop conditions.

FIGURE 17-26: BUS COLLISION DURING START CONDITION (SDA ONLY)



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18.1 Baud Rate Generator (BRG)

The BRG is a dedicated 8-bit or 16-bit generator that supports both the Asynchronous and Synchronous modes of the EUSART. By default, the BRG operates in 8-bit mode; setting the BRG16 bit (BAUDCON<3>) selects 16-bit mode.

The SPBRGH:SPBRG register pair controls the period of a free-running timer. In Asynchronous mode, bits, BRGH (TXSTA<2>) and BRG16 (BAUDCON<3>), also control the baud rate. In Synchronous mode, BRGH is ignored. Table 18-1 shows the formula for computation of the baud rate for different EUSART modes which only apply in Master mode (internally generated clock).

Given the desired baud rate and FOSC, the nearest integer value for the SPBRGH:SPBRG registers can be calculated using the formulas in Table 18-1. From this, the error in baud rate can be determined. An example calculation is shown in Example 18-1. Typical baud rates and error values for the various Asynchronous modes are shown in Table 18-2. It may be advantageous to use the high baud rate (BRGH = 1) or the 16-bit BRG to reduce the baud rate error, or achieve a slow baud rate for a fast oscillator frequency.

Writing any value (even the same value) to the SPBRGH:SPBRG registers immediately reloads the BRG timer. This may corrupt a transmission or reception already in progress. This ensures the BRG does not wait for a timer overflow before outputting the new baud rate.

18.1.1 OPERATION IN POWER-MANAGED MODES

The device clock is used to generate the desired baud rate. When one of the power-managed modes is entered, the new clock source may be operating at a different frequency. This may require an adjustment to the value in the SPBRG register pair.

18.1.2 SAMPLING

The data on the RX pin is sampled three times by a majority detect circuit to determine if a high or a low level is present at the RX pin when SYNC is clear or when BRG16 and BRGH are both not set. The data on the RX pin is sampled once when SYNC is set or when BRGH16 and BRGH are both set.

TABLE 18-1: BAUD RATE FORMULAS

Configuration Bits			BRG/EUSART Mode	Baud Rate Formula
SYNC	BRG16	BRGH		
0	0	0	8-bit/Asynchronous	FOSC/[64 (n + 1)]
0	0	1	8-bit/Asynchronous	FOSC/[16 (n + 1)]
0	1	0	16-bit/Asynchronous	
0	1	1	16-bit/Asynchronous	FOSC/[4 (n + 1)]
1	0	x	8-bit/Synchronous	
1	1	x	16-bit/Synchronous	

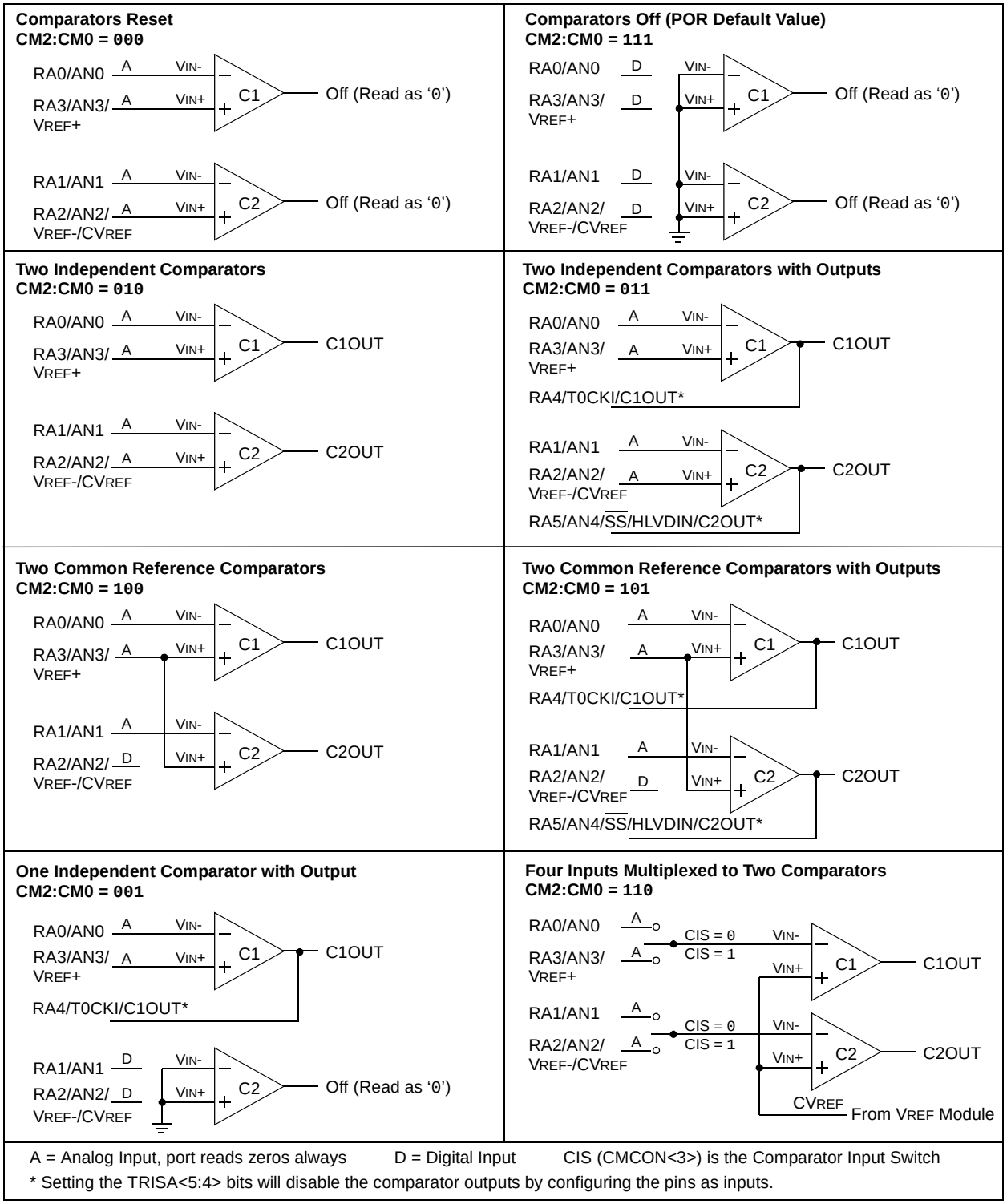
Legend: x = Don't care, n = value of SPBRGH:SPBRG register pair

20.1 Comparator Configuration

There are eight modes of operation for the comparators, shown in Figure 20-1. Bits, CM2:CM0 of the CMCON register, are used to select these modes. The TRISA register controls the data direction of the comparator pins for each mode. If the Comparator mode is changed, the comparator output level may not be valid for the specified mode change delay shown in **Section 26.0 "Electrical Characteristics"**.

Note:	Comparator interrupts should be disabled during a Comparator mode change; otherwise, a false interrupt may occur.

FIGURE 20-1: COMPARATOR I/O OPERATING MODES



A = Analog Input, port reads zeros always D = Digital Input CIS (CMCON<3>) is the Comparator Input Switch

* Setting the TRISA<5:4> bits will disable the comparator outputs by configuring the pins as inputs.

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22.0 HIGH/LOW-VOLTAGE DETECT (HLVD)

PIC18F2525/2620/4525/4620 devices have a High/Low-Voltage Detect module (HLVD). This is a programmable circuit that allows the user to specify both a device voltage trip point and the direction of change from that point. If the device experiences an excursion past the trip point in that direction, an interrupt flag is set. If the interrupt is enabled, the program execution will branch to the interrupt vector address and the software can then respond to the interrupt.

The High/Low-Voltage Detect Control register (Register 22-1) completely controls the operation of the HLVD module. This allows the circuitry to be "turned off" by the user under software control, which minimizes the current consumption for the device.

The block diagram for the HLVD module is shown in Figure 22-1.

REGISTER 22-1: HLVDCON: HIGH/LOW-VOLTAGE DETECT CONTROL REGISTER

R/W-0	U-0	R-0	R/W-0	R/W-0	R/W-1	R/W-0	R/W-1
VDIRMAG	—	IRVST	HLVDEN	HLVDL3(1)	HLVDL2(1)	HLVDL1(1)	HLVDL0(1)
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7 **VDIRMAG:** Voltage Direction Magnitude Select bit
1 = Event occurs when voltage equals or exceeds trip point (HLVDL3:HLDVL0)
0 = Event occurs when voltage equals or falls below trip point (HLVDL3:HLVDL0)

bit 6 **Unimplemented:** Read as '0'

bit 5 **IRVST:** Internal Reference Voltage Stable Flag bit
1 = Indicates that the voltage detect logic will generate the interrupt flag at the specified voltage range
0 = Indicates that the voltage detect logic will not generate the interrupt flag at the specified voltage range and the HLVD interrupt should not be enabled

bit 4 **HLVDEN:** High/Low-Voltage Detect Power Enable bit
1 = HLVD enabled
0 = HLVD disabled

bit 3-0 **HLVDL3:HLVDL0:** Voltage Detection Limit bits(1)
1111 = External analog input is used (input comes from the HLVDIN pin)
1110 = Maximum setting
.
.
.
0000 = Minimum setting

Note 1: See Table 26-4 in **Section 26.0 "Electrical Characteristics"**for the specifications.

The module is enabled by setting the HLVDEN bit. Each time that the HLVD module is enabled, the circuitry requires some time to stabilize. The IRVST bit is a read-only bit and is used to indicate when the circuit is stable. The module can only generate an interrupt after the circuit is stable and IRVST is set.

The VDIRMAG bit determines the overall operation of the module. When VDIRMAG is cleared, the module monitors for drops in VDD below a predetermined set point. When the bit is set, the module monitors for rises in VDD above the set point.

BZ **Branch if Zero**

Syntax: BZ n

Operands: $-128 \le n \le 127$

Operation: if Zero bit is '1',
(PC) + 2 + 2n → PC

Status Affected: None

Encoding:

1110	0000	nnnn	nnnn

Description: If the Zero bit is '1', then the program will branch.
The 2's complement number '2n' is added to the PC. Since the PC will have incremented to fetch the next instruction, the new address will be PC + 2 + 2n. This instruction is then a two-cycle instruction.

Words: 1

Cycles: 1(2)

Q Cycle Activity:
If Jump:

Q1	Q2	Q3	Q4
Decode	Read literal 'n'	Process Data	Write to PC
No operation	No operation	No operation	No operation

If No Jump:

Q1	Q2	Q3	Q4
Decode	Read literal 'n'	Process Data	No operation

Example: `HERE BZ Jump`

Before Instruction
PC = address (HERE)
After Instruction
If Zero = 1;
PC = address (Jump)
If Zero = 0;
PC = address (HERE + 2)

CALL **Subroutine Call**

Syntax: CALL k {,s}

Operands: $0 \le k \le 1048575$
$s \in [0,1]$

Operation: (PC) + 4 → TOS,
k → PC<20:1>;
if s = 1,
(W) → WS,
(STATUS) → STATUSS,
(BSR) → BSRS

Status Affected: None

Encoding:

1st word (k<7:0>)	1110	110s	$k_7$kkk	kkkk$_0$
2nd word(k<19:8>)	1111	k_{19}kkk	kkkk	kkkk$_8$

Description: Subroutine call of entire 2-Mbyte memory range. First, return address (PC + 4) is pushed onto the return stack. If 's' = 1, the W, STATUS and BSR registers are also pushed into their respective shadow registers, WS, STATUSS and BSRS. If 's' = 0, no update occurs (default). Then, the 20-bit value 'k' is loaded into PC<20:1>. CALL is a two-cycle instruction.

Words: 2

Cycles: 2

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal 'k'<7:0>,	PUSH PC to stack	Read literal 'k'<19:8>, Write to PC
No operation	No operation	No operation	No operation

Example: `HERE CALL THERE, 1`

Before Instruction
PC = address (HERE)
After Instruction
PC = address (THERE)
TOS = address (HERE + 4)
WS = W
BSRS = BSR
STATUSS = STATUS

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COMF **Complement f**

Syntax: COMF f {,d {,a}}

Operands: $0 \le f \le 255$
$d \in [0,1]$
$a \in [0,1]$

Operation: $(\bar{f}) \rightarrow$ dest

Status Affected: N, Z

Encoding:

0001	11da	ffff	ffff

Description: The contents of register 'f' are complemented. If 'd' is '0', the result is stored in W. If 'd' is '1', the result is stored back in register 'f' (default).
If 'a' is '0', the Access Bank is selected. If 'a' is '1', the BSR is used to select the GPR bank.
If 'a' is '0' and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever $f \le 95$ (5Fh). See **Section 24.2.3 "Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode"** for details.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	Write to destination

Example: COMF REG, 0, 0

Before Instruction
REG = 13h
After Instruction
REG = 13h
W = ECh

CPFSEQ **Compare f with W, Skip if f = W**

Syntax: CPFSEQ f {,a}

Operands: $0 \le f \le 255$
$a \in [0,1]$

Operation: (f) – (W),
skip if (f) = (W)
(unsigned comparison)

Status Affected: None

Encoding:

0110	001a	ffff	ffff

Description: Compares the contents of data memory location 'f' to the contents of W by performing an unsigned subtraction.
If 'f' = W, then the fetched instruction is discarded and a NOP is executed instead, making this a two-cycle instruction.
If 'a' is '0', the Access Bank is selected. If 'a' is '1', the BSR is used to select the GPR bank.
If 'a' is '0' and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever $f \le 95$ (5Fh). See **Section 24.2.3 "Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode"** for details.

Words: 1

Cycles: 1(2)
Note: 3 cycles if skip and followed by a 2-word instruction.

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	No operation

If skip:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation

If skip and followed by 2-word instruction:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation
No operation	No operation	No operation	No operation

Example:
```
HERE    CPFSEQ REG, 0
NEQUAL  :
EQUAL   :
```

Before Instruction
PC Address = HERE
W = ?
REG = ?
After Instruction
If REG = W;
PC = Address (EQUAL)
If REG ≠ W;
PC = Address (NEQUAL)

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CPFSGT **Compare f with W, Skip if f > W**

Syntax: CPFSGT f {,a}

Operands: $0 \le f \le 255$
$a \in [0,1]$

Operation: (f) – (W),
skip if (f) > (W)
(unsigned comparison)

Status Affected: None

Encoding:

0110	010a	ffff	ffff

Description: Compares the contents of data memory location 'f' to the contents of the W by performing an unsigned subtraction.
If the contents of 'f' are greater than the contents of WREG, then the fetched instruction is discarded and a NOP is executed instead, making this a two-cycle instruction.
If 'a' is '0', the Access Bank is selected.
If 'a' is '1', the BSR is used to select the GPR bank.
If 'a' is '0' and the extended instruction set is enabled, this instruction operates in Indexed Literal Offset Addressing mode whenever $f \le 95$ (5Fh). See **Section 24.2.3 "Byte-Oriented and Bit-Oriented Instructions in Indexed Literal Offset Mode"** for details.

Words: 1

Cycles: 1(2)
Note: 3 cycles if skip and followed by a 2-word instruction.

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	No operation

If skip:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation

If skip and followed by 2-word instruction:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation
No operation	No operation	No operation	No operation

Example:
```
HERE      CPFSGT REG, 0
NGREATER  :
GREATER   :
```
Before Instruction
PC = Address (HERE)
W = ?
After Instruction
If REG > W;
PC = Address (GREATER)
If REG ≤ W;
PC = Address (NGREATER)

CPFSLT **Compare f with W, Skip if f < W**

Syntax: CPFSLT f {,a}

Operands: $0 \le f \le 255$
$a \in [0,1]$

Operation: (f) – (W),
skip if (f) < (W)
(unsigned comparison)

Status Affected: None

Encoding:

0110	000a	ffff	ffff

Description: Compares the contents of data memory location 'f' to the contents of W by performing an unsigned subtraction.
If the contents of 'f' are less than the contents of W, then the fetched instruction is discarded and a NOP is executed instead, making this a two-cycle instruction.
If 'a' is '0', the Access Bank is selected.
If 'a' is '1', the BSR is used to select the GPR bank.

Words: 1

Cycles: 1(2)
Note: 3 cycles if skip and followed by a 2-word instruction.

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process Data	No operation

If skip:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation

If skip and followed by 2-word instruction:

Q1	Q2	Q3	Q4
No operation	No operation	No operation	No operation
No operation	No operation	No operation	No operation

Example:
```
HERE    CPFSLT REG, 1
NLESS   :
LESS    :
```
Before Instruction
PC = Address (HERE)
W = ?
After Instruction
If REG < W;
PC = Address (LESS)
If REG ≥ W;
PC = Address (NLESS)

25.2 MPASM Assembler

The MPASM Assembler is a full-featured, universal macro assembler for all PIC MCUs.

The MPASM Assembler generates relocatable object files for the MPLINK Object Linker, Intel® standard HEX files, MAP files to detail memory usage and symbol reference, absolute LST files that contain source lines and generated machine code and COFF files for debugging.

The MPASM Assembler features include:

- Integration into MPLAB IDE projects
- User-defined macros to streamline assembly code
- Conditional assembly for multi-purpose source files
- Directives that allow complete control over the assembly process

25.3 MPLAB C18 and MPLAB C30 C Compilers

The MPLAB C18 and MPLAB C30 Code Development Systems are complete ANSI C compilers for Microchip's PIC18 and PIC24 families of microcontrollers and the dsPIC30 and dsPIC33 family of digital signal controllers. These compilers provide powerful integration capabilities, superior code optimization and ease of use not found with other compilers.

For easy source level debugging, the compilers provide symbol information that is optimized to the MPLAB IDE debugger.

25.4 MPLINK Object Linker/ MPLIB Object Librarian

The MPLINK Object Linker combines relocatable objects created by the MPASM Assembler and the MPLAB C18 C Compiler. It can link relocatable objects from precompiled libraries, using directives from a linker script.

The MPLIB Object Librarian manages the creation and modification of library files of precompiled code. When a routine from a library is called from a source file, only the modules that contain that routine will be linked in with the application. This allows large libraries to be used efficiently in many different applications.

The object linker/library features include:

- Efficient linking of single libraries instead of many smaller files
- Enhanced code maintainability by grouping related modules together
- Flexible creation of libraries with easy module listing, replacement, deletion and extraction

25.5 MPLAB ASM30 Assembler, Linker and Librarian

MPLAB ASM30 Assembler produces relocatable machine code from symbolic assembly language for dsPIC30F devices. MPLAB C30 C Compiler uses the assembler to produce its object file. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. Notable features of the assembler include:

- Support for the entire dsPIC30F instruction set
- Support for fixed-point and floating-point data
- Command line interface
- Rich directive set
- Flexible macro language
- MPLAB IDE compatibility

25.6 MPLAB SIM Software Simulator

The MPLAB SIM Software Simulator allows code development in a PC-hosted environment by simulating the PIC MCUs and dsPIC® DSCs on an instruction level. On any given instruction, the data areas can be examined or modified and stimuli can be applied from a comprehensive stimulus controller. Registers can be logged to files for further run-time analysis. The trace buffer and logic analyzer display extend the power of the simulator to record and track program execution, actions on I/O, most peripherals and internal registers.

The MPLAB SIM Software Simulator fully supports symbolic debugging using the MPLAB C18 and MPLAB C30 C Compilers, and the MPASM and MPLAB ASM30 Assemblers. The software simulator offers the flexibility to develop and debug code outside of the hardware laboratory environment, making it an excellent, economical software development tool.

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26.2 DC Characteristics: Power-Down and Supply Current PIC18F2525/2620/4525/4620 (Industrial) PIC18LF2525/2620/4525/4620 (Industrial) (Continued)

PIC18LF2525/2620/4525/4620 (Industrial)	Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial
PIC18F2525/2620/4525/4620 (Industrial, Extended)	Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended

Param No.	Device	Typ	Max	Units	Conditions		
	Supply Current (IDD)(2)						
	PIC18LFX525/X620	13	25	µA	-40°C	VDD = 2.0V	FOSC = 31 kHz (**RC_RUN** mode, INTRC source)
		13	22	µA	+25°C		
		14	25	µA	+85°C		
	PIC18LFX525/X620	42	61	µA	-40°C	VDD = 3.0V	
		34	46	µA	+25°C		
		28	45	µA	+85°C		
	All devices	103	160	µA	-40°C	VDD = 5.0V	
		82	130	µA	+25°C		
		67	120	µA	+85°C		
	Extended devices only	71	230	µA	+125°C		
	PIC18LFX525/X620	320	440	µA	-40°C	VDD = 2.0V	FOSC = 1 MHz (**RC_RUN** mode, INTOSC source)
		330	440	µA	+25°C		
		330	440	µA	+85°C		
	PIC18LFX525/X620	630	800	µA	-40°C	VDD = 3.0V	
		590	720	µA	+25°C		
		570	700	µA	+85°C		
	All devices	1.2	1.6	mA	-40°C	VDD = 5.0V	
		1.0	1.5	mA	+25°C		
		1.0	1.5	mA	+85°C		
	Extended devices only	1.0	1.5	mA	+125°C		

Legend: Shading of rows is to assist in readability of the table.

Note 1: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to VDD or VSS and all features that add delta current disabled (such as WDT, Timer1 Oscillator, BOR, etc.).

2: The supply current is mainly a function of operating voltage, frequency and mode. Other factors, such as I/O pin loading and switching rate, oscillator type and circuit, internal code execution pattern and temperature, also have an impact on the current consumption.

The test conditions for all IDD measurements in active operation mode are:

OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD or VSS;

$\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.

3: When operation below -10°C is expected, use T1OSC High-Power mode, where LPT1OSC (CONFIG3H<2>) = 0. When operation will always be above -10°C, then the low-power Timer1 oscillator may be selected.

4: BOR and HLVD enable internal band gap reference. With both modules enabled, current consumption will be less than the sum of both specifications.

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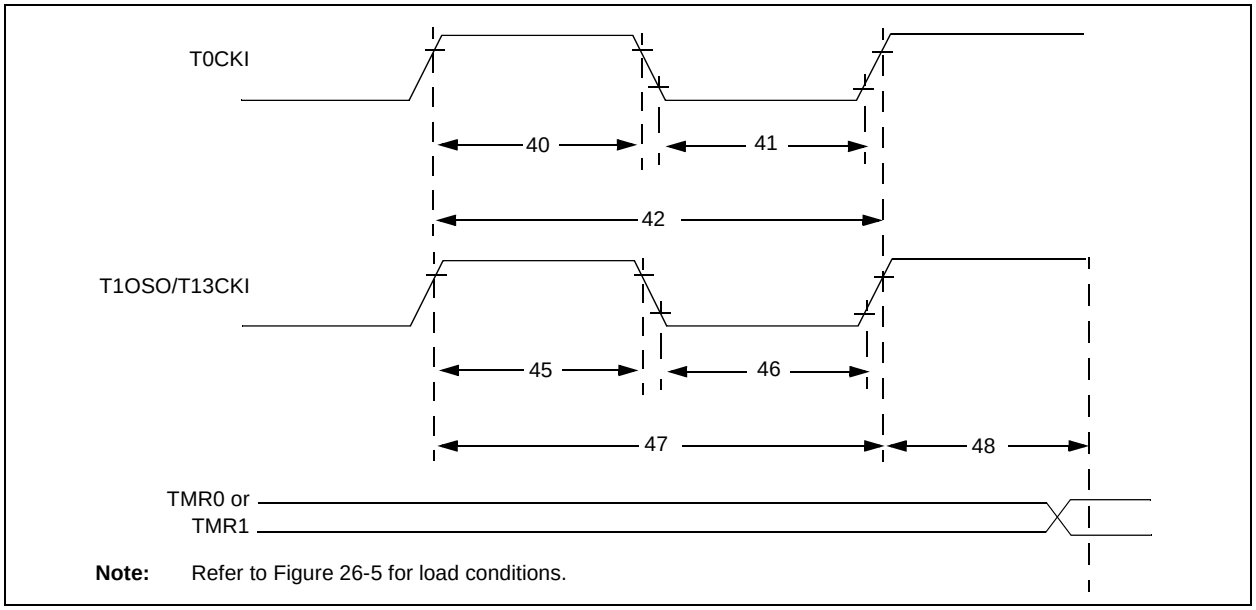
FIGURE 26-10: TIMER0 AND TIMER1 EXTERNAL CLOCK TIMINGS



Note: Refer to Figure 26-5 for load conditions.

TABLE 26-11: TIMER0 AND TIMER1 EXTERNAL CLOCK REQUIREMENTS

Param No.	Symbol	Characteristic			Min	Max	Units	Conditions
40	Tt0H	T0CKI High Pulse Width		No prescaler	0.5 TCY + 20	—	ns	
				With prescaler	10	—	ns	
41	Tt0L	T0CKI Low Pulse Width		No prescaler	0.5 TCY + 20	—	ns	
				With prescaler	10	—	ns	
42	Tt0P	T0CKI Period		No prescaler	TCY + 10	—	ns	
				With prescaler	Greater of: 20 ns or (TCY + 40)/N	—	ns	N = prescale value (1, 2, 4,..., 256)
45	Tt1H	T13CKI High Time	Synchronous, no prescaler		0.5 TCY + 20	—	ns	
			Synchronous, with prescaler	PIC18**F**XXXX	10	—	ns	
				PIC18**LF**XXXX	25	—	ns	VDD = 2.0V
			Asynchronous	PIC18**F**XXXX	30	—	ns	
				PIC18**LF**XXXX	50	—	ns	VDD = 2.0V
46	Tt1L	T13CKI Low Time	Synchronous, no prescaler		0.5 TCY + 5	—	ns	
			Synchronous, with prescaler	PIC18**F**XXXX	10	—	ns	
				PIC18**LF**XXXX	25	—	ns	VDD = 2.0V
			Asynchronous	PIC18**F**XXXX	30	—	ns	
				PIC18**LF**XXXX	50	—	ns	VDD = 2.0V
47	Tt1P	T13CKI Input Period	Synchronous		Greater of: 20 ns or (TCY + 40)/N	—	ns	N = prescale value (1, 2, 4, 8)
			Asynchronous		60	—	ns	
	Ft1	T13CKI Oscillator Input Frequency Range			DC	50	kHz	
48	Tcke2tmrl	Delay from External T13CKI Clock Edge to Timer Increment			2 TOSC	7 TOSC	—	

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FIGURE 27-9: TYPICAL WDT CURRENT vs. VDD ACROSS TEMPERATURE (WDT DELTA CURRENT IN SLEEP MODE)

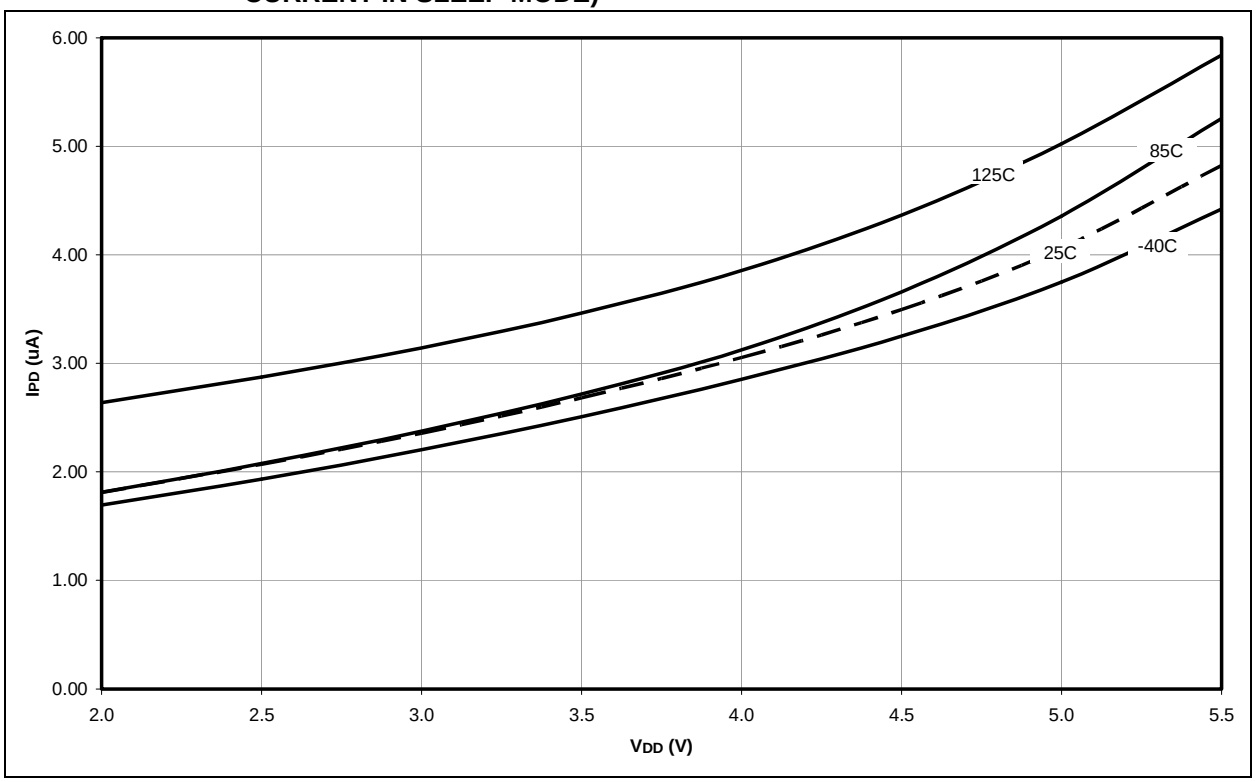

FIGURE 27-10: MAXIMUM WDT CURRENT vs. VDD ACROSS TEMPERATURE (WDT DELTA CURRENT IN SLEEP MODE)

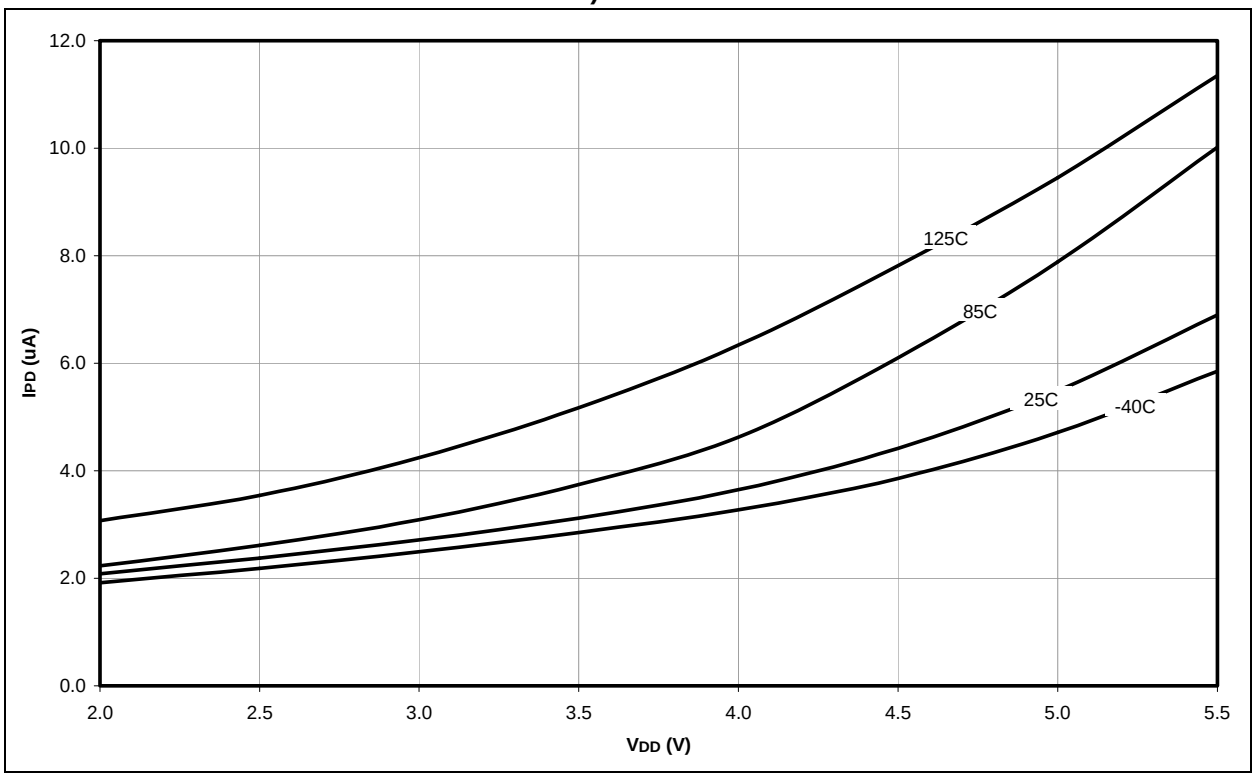

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FIGURE 27-27: TYPICAL IDD vs. FOSC, 4 MHz TO 40 MHz (PRI_IDLE MODE, 25°C)

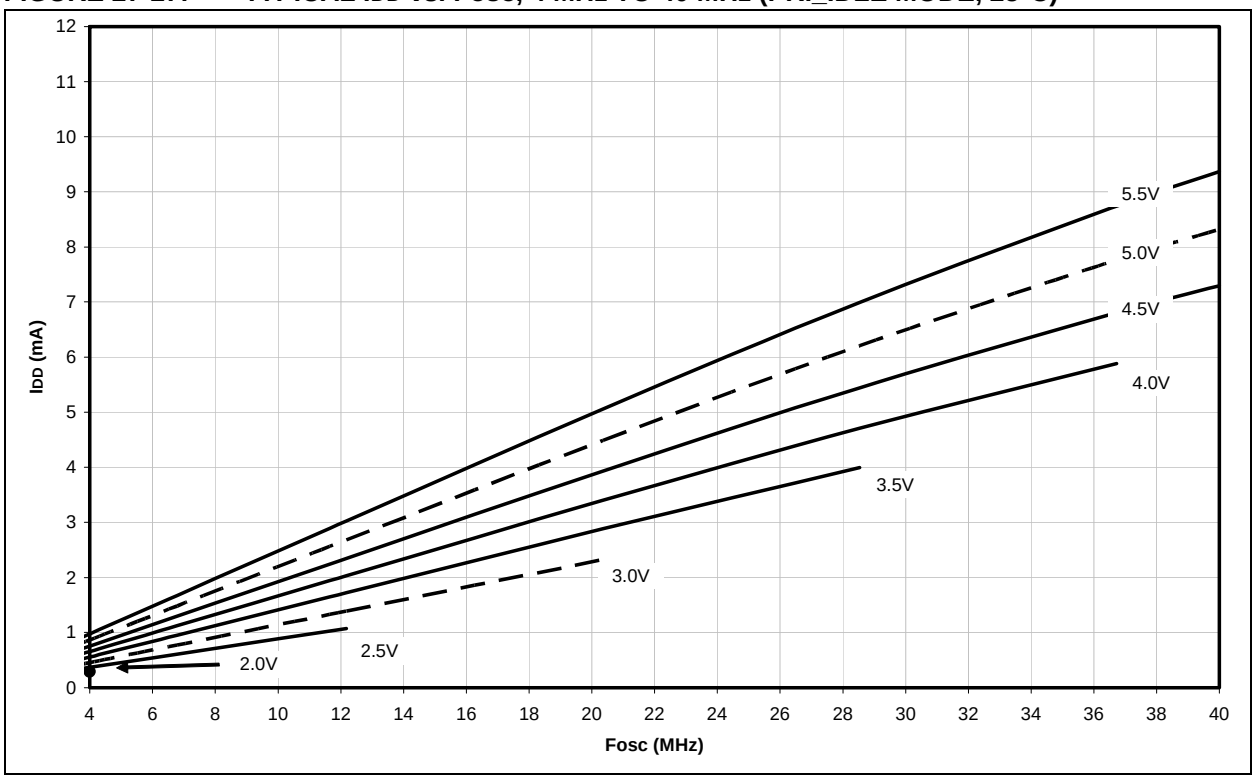


FIGURE 27-28: MAXIMUM IDD vs. FOSC, 4 MHz TO 40 MHz (PRI_IDLE MODE, -40°C TO +125°C)

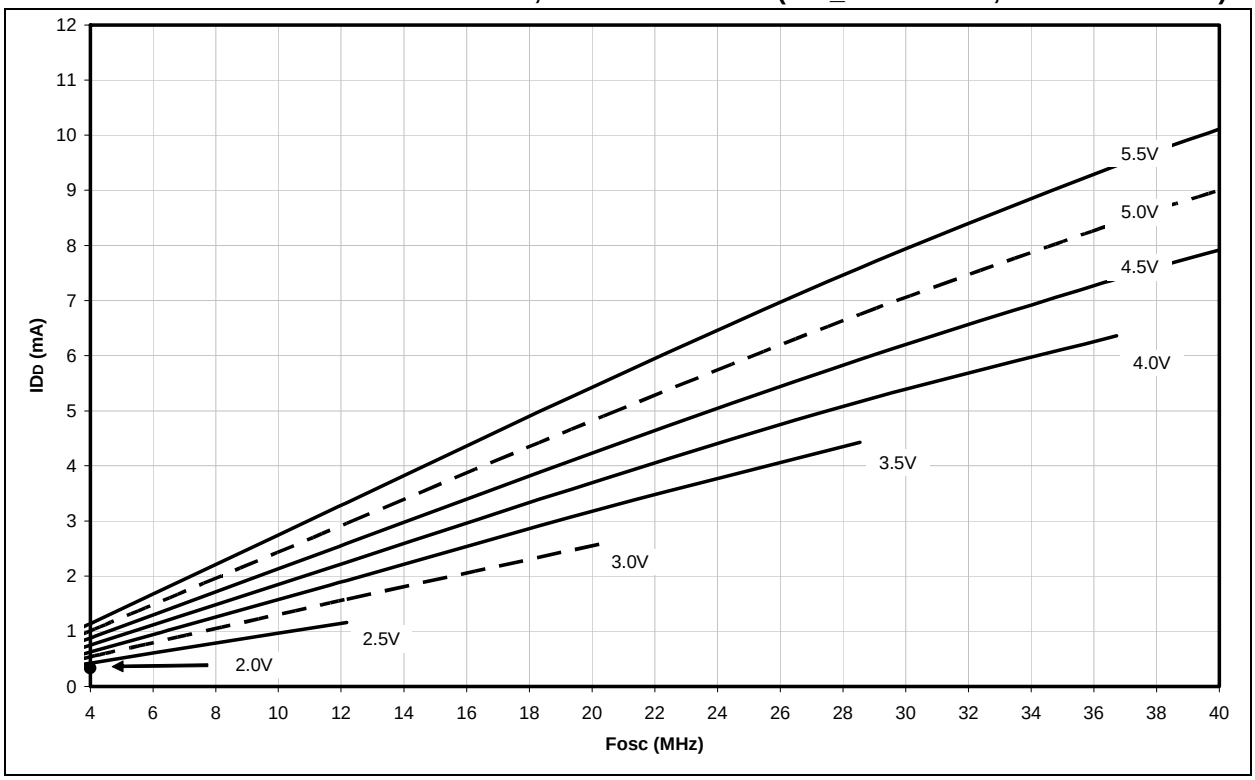


FIGURE 27-37: INTOSC FREQUENCY vs. VDD, TEMPERATURE (-40°C, +25°C, +85°C, +125°C)

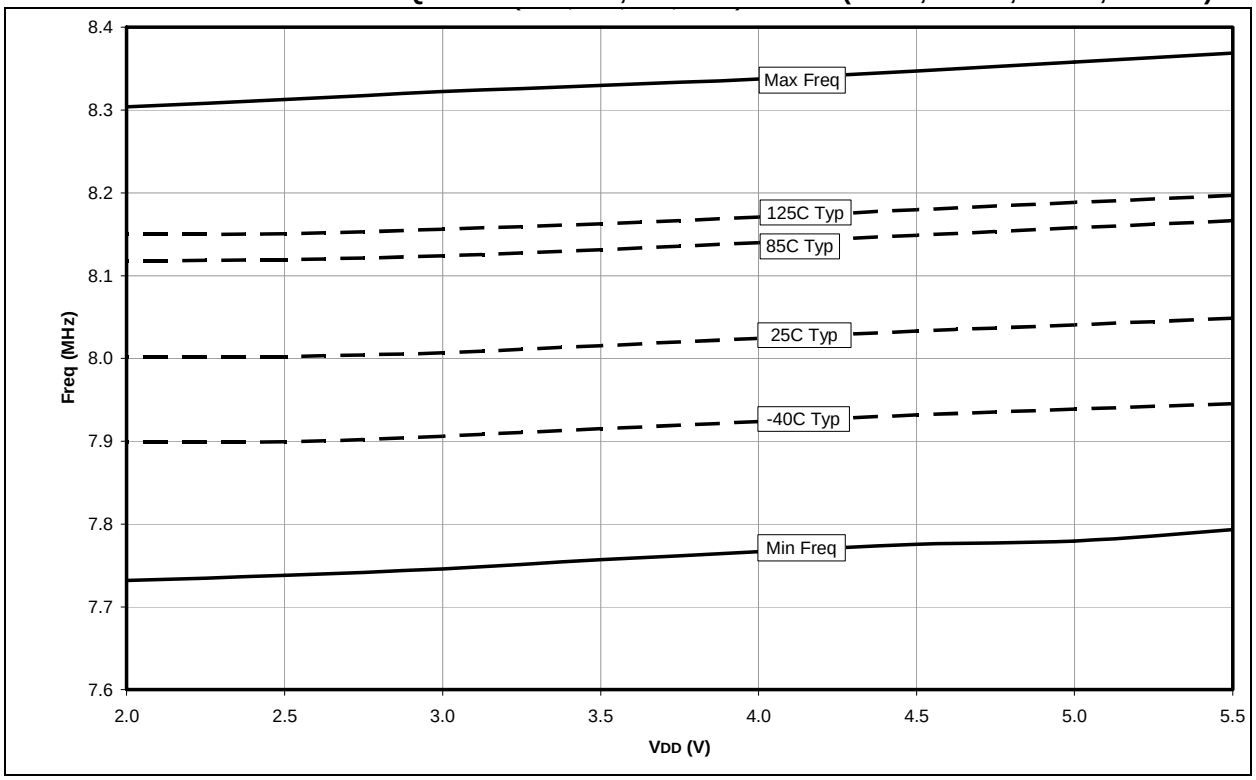
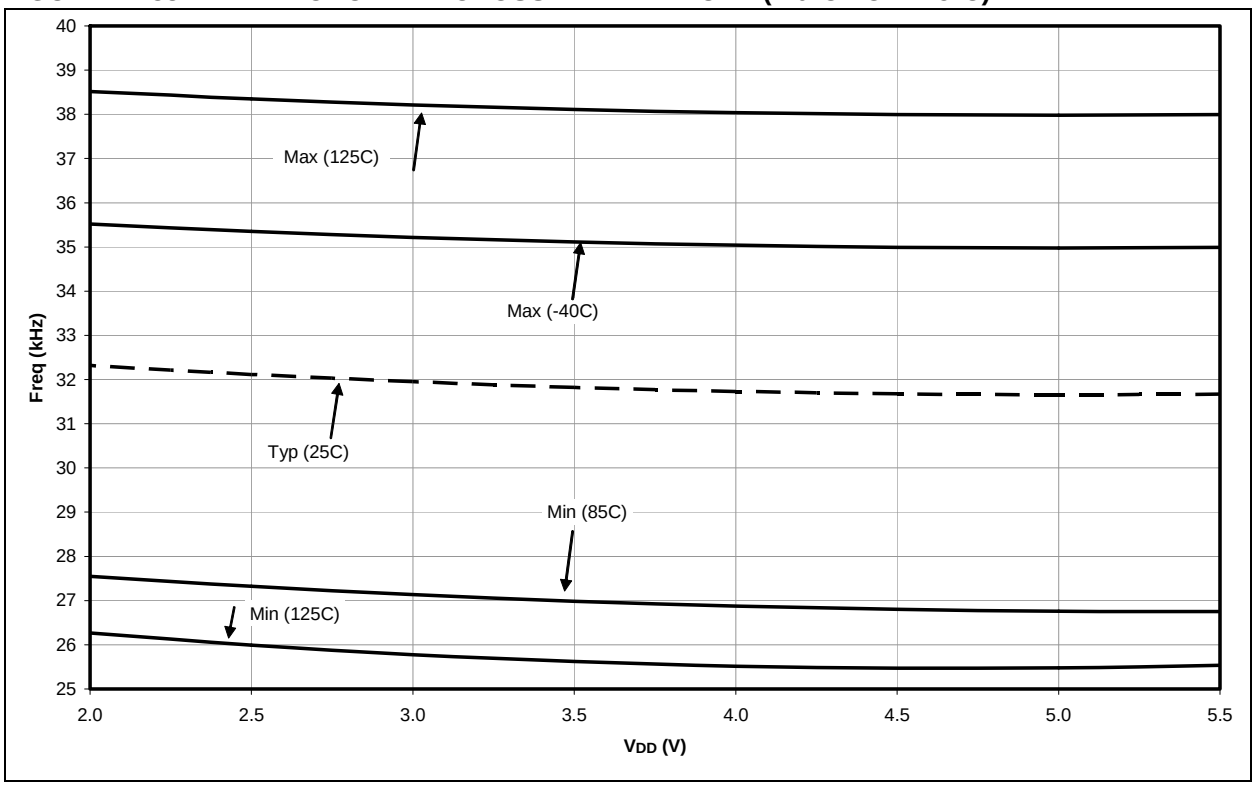


FIGURE 27-38: INTRC vs. VDD ACROSS TEMPERATURE (-40°C TO +125°C)



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